

A1  
cont.

mounting surface (bottom surface), predetermined numbers of solder balls which are formed on the mounting surface (bottom surface) and which connect the semiconductor device to the principle surface of the printed wiring substrate, and the like. On corners of the bottom surface of the body portion, reinforcing pads are provided, respectively. A plurality of the solder balls are positioned (mounted) on each of the reinforcing pads. Each of the reinforcing pads has a periphery adjacent to each of the solder balls mounted thereon that is at least semicircular, when seen in plan view as in Figure 5A.--.

IN THE CLAIMS:

Cancel claims 1-7.

Add the following new claims:

A2

--8. (new) A semiconductor device having a mounting surface that is to be attached to a circuit board, the device comprising:

plural reinforcing pads on said mounting surface of said semiconductor device that are each adjacent to a respective corner of said mounting surface; and

plural first solder balls on each of said reinforcing pads,

wherein said reinforcing pads each having a periphery adjacent to said plural ones of said first solder balls that, when seen in a plan view of said mounting surface, is at least semicircular.